

4/3,AB,LS/1 (Item 1 from file: 347)
DIALOG(R)File 347:JAPIO
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02360894

MANUFACTURE OF INNER LAYER CIRCUIT BOARD

PUB. NO.: 62-277794 A]

PUBLISHED: December 02, 1987 (19871202)

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APPL. NO.: 61-121453 [JP 86121453]

FILED: May 27, 1986 (19860527)

4/3,AB,LS/2 (Item 1 from file: 351)
DIALOG(R)File 351:Derwent WPI
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007382889

WPI Acc No: 1988-016824/ 198803

Inner circuit plate for multilayer printed circuit board - has substrate
impregnated with thermosetting resin, contg. inorganic filler and rubber,
and metal plate. NoAbstract Dwg 3/3

Patent Assignee: HITACHI CHEM CO LTD (HITB)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 62277794	A	19871202	JP 86121453	A	19860527	198803 B

Priority Applications (No Type Date): JP 86121453 A 19860527

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
JP 62277794	A		3		

4/3,AB,LS/3 (Item 1 from file: 345)
DIALOG(R)File 345:Inpadoc/Fam.& Legal Stat
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Acc no: 8006253

Basic Patent (No,Kind,Date): JP 62277794 A2 871202

<No. of Patents: 001>

MANUFACTURE OF INNER LAYER CIRCUIT BOARD (English)

Patent Assignee: HITACHI CHEMICAL CO LTD

Author (Inventor): NAKAMURA HIDEHIRO; FUKUTOMI NAOKI; IWASAKI YORIO; KOJIMA
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IPC: *H05K-003/46;

Derwent WPI Acc No: C 88-016824

Language of Document: Japanese

Patent Family:

Patent No	Kind	Date	Applic No	Kind	Date
JP 62277794	A2	871202	JP 86121453	A	860527 (BASIC)

Priority (No,Kind,Date): JP 86121453 A 860527